Test Research, Inc. (TRI), a leading test and inspection systems provider for the electronics manufacturing industry, returns to Nepcon Japan in 2014 with a powerful and cost-effective one stop solution lineup for inspecting and testing PCB assemblies. Test Research, Inc. invites you to visit booth EAST25-20 from January 15-17 at the Tokyo Big Sight for an on-site demonstration of the following systems, including two 2013 industry award winning systems.

TR7500 SIII 3D AOI

- Total Coverage 2D + 3D AOI
- True 3D Profile Measurement
- Next Generation Easy Programming GUI
- High Performance Design for Automotive and HDI

TR7007 SII DUAL LANE 3D SPI

- New GUI With 5-step Easy Programming
- Independent Dual Lane Project Control
- Closed Loop Integration
- Dynamic WBGR Imaging for Fast Fiducial Mark Scanning

Test & Measurement World BEST in TEST 2013 AWARD WINNER

TR7700M SIII AOI

- High Speed Multi-Phase Inspection
  10 μm 60 cm²/sec
  15 μm 120 cm²/sec
- New GUI for Easy Programming
- Auto-tuning Intelligent Automated Conveyor System

TR5001 INLINE ICT

- Automatic Load and Unload
- Fast Insertion Mechanism
- Conforms to SMEMA Standards
- Dual Stage Press Unit
- Powerful Boundary Scan Test Solutions
- Easy to Use On-board Programming Software
- Bosch CM Exclusive ICT Solution

TR7600X SII 3D AXI

- High-speed Inline 3D X-ray Inspection
- High Resolution Mode for 01005 Components
- BGA, PoP, Press-fit, PTH, QFN, Inspection
- Multiple Resolutions in One Program
- Board Size up to 900 x 460 mm
- Block Scan 3D Slice Imaging

TR5001T SII TINY ICT

EM asia Innovation Awards 创新奖 2013

- Multi-ICT Parallel Testing
- Boundary Scan Test
- Serial Device Programming
- Audio Analyzer
- Data Acquisition
- Advanced Analog and Digital Testing with Programmable DUT Power Supplies

YMS LITE

- Defect Image Analysis & Reporting
- SPI, Pre/Post-reflow AOI & AXI Integration
- Alarm Module